Doc description: Information Disclosure Statement (IDS) Filed

FUNDAMORS (04-49)

formation Disclosure Statement (IDS) Filed

U.S. Patent and Trainair Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Restuction Act of 1955, no persons are required to respond to a collection of information unless to contains a valid foreign member.

INFORMATION DISCLOSURE
STATEMENT BY APPLICANT
( Not for submission under 37 CFR 1.99)

Application Number		10542040			
Filing Date		2006-02-06			
First Named Inventor	John	n Mize			
Art Unit		1795			
Examiner Name Jason		n Berman			
Attorney Docket Number		H0004870 70759 US 4016			

	-			
Patent Number	Kind Code <sup>1</sup>	Issue Date	of cited Document	Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear
				Patent Number Code   Issue Date   Name of Patentee of Applicant

If you wish to add additional U.S. Patent citation information please click the Add button.

U.S.PATENT A		

Examiner Initial*	Cite No	Publication Number	Kind Code <sup>1</sup>	Publication Date	Name of Patentee or Applicant of cited Document	Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear
	1	20080149598	A1	2008-06-26	Tokyo Electron Limited	
	2	20070273287	A1	2007-11-29	Nagisa Kuwahara, et al	
	3	20080100221	A1	2008-05-01	Nagisa Kuwahara, et al	
	4	20080289958	A1	2008-11-27	Honeywell International Inc.	
	5	20050236270	A1	2005-10-27	Heraeus, Inc.	

## INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)

Application Number		10542040		
Filing Date		2006-02-06		
First Named Inventor John Art Unit		n Mize		
		1795		
xaminer Name Jaso		on Berman		
Attorney Docket Number		H0004870.70759 US -4015		

6	20070240795	A1	2007-10-18	Ulvac Materials, Inc.
7	20080003385	A1	2008-01-03	Kabushiki Kaisha Kobe Seiko Sho
8	20030168131	A1	2003-09-11	Christopher A. Michaluk, et al.
9	20070163878	A1	2007-07-19	Nippon Mining & Metals Co., Ltd.
10	20030188685	A1	2003-10-09	Applied Materials, Inc.
11	20050271984	A1	2005-12-08	Applied Materials, Inc.
12	20060292310	A1	2006-12-28	Applied Materials, Inc.
13	20070056688	A1	2007-03-15	Jaeyeon Kim, et al.
14	20070059460	A1	2007-03-15	Applied Materials, Inc.
15	20050064248	A1	2005-03-24	Robert J. O'Donnell, et al.
16	20050181617	A1	2005-08-18	William Frederick Bosch

## 

Attorney Docket Number

H0004870,70759 US -4015

	17	20070166477	A1	2007-07-19	Lam Researc	h Corporation		
If you wisl	h to a	dd additional U.S. Pub	lished App	plication citation	n information	please click the Add but	ton.	-
				FOREIGN PAT	TENT DOCUM	MENTS		
Examiner Initial*	Cite No	Foreign Document Number <sup>3</sup>	Country Code <sup>2</sup> i	Kind Code4	Publication Date	Name of Patentee or Applicant of cited Document	Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear	<b>T</b> 5
	1					The second secon		

Examiner Citie Initials\* No. PATENT LITERATURE DOCUMENTS

| Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, pages(s), volume-issue number(s), publisher, city and/or country where published.

If you wish to add additional non-patent literature document citation information please click the Add button

## **EXAMINER SIGNATURE**

Examiner Signature Date Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through a citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

See Kind Codes of USPTO Patent Documents at www.USPTO\_GOV or MPEP 901.04. Enter office that issued the occument, by the two-letter code (WIPO Standard ST.3). For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document, 4 kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. Applicant is to place a check mark here if English language translation is attached.

1